Contribution ID: **88** Type: **not specified**

Bonding test procedure developed for the assembly of BM@N STS modules

Friday 23 October 2020 15:20 (20 minutes)

RFBR grant 18-02-40047
The Silicon Tracking System (STS) of BM@N experiment will be based on modules with double-sided microstrip silicon sensors, which have been developed for the CBM experiment at FAIR. Each module consists of a double-sided sensor, two front-end boards with 8 ASICs each and a set of low-mass aluminum microcables. During the module assembly microcables are Tab-bonded to the sensor and readout ASICs. Each module has 1024 channels on both sides. For the quality assurance of the bonding parameters a dedicated procedure based on the noise per channel measurements in a Pogo-Pin test circuit was developed.

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Session Classification: Parallel session IV